U.S. PTO 12/285375

10/02/2008

10-20-2008 MMERCE Form PTO-1595 (Rev. 08/08) ark Office OMB No. 0651-0027 (exp. 9/30/2008) **RECORDATION FORM CO** PATENTS OF 103530410 To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below. 2. Name and address of receiving party(ies) 1. Name of conveying party(ies): Hiromi Ogata Sony Corporation Internal Address: X No Yes Additional name(s) of conveying party(ies) attached? Street Address: 3. Nature of conveyance/Execution Date(s): 1-7-1 Konan Minato-Ku, Tokyo Execution Date(s): September 19, 2008 108-0075 **JAPAN** Merger Change of Name x Assignment Joint Research Agreement Security Agreement City: Government Interest Assignment State: Executive Order 9424, Confirmatory License Zip: Country: Additional name(s) & address(es) x No Yes attached? X This document is being filed together with a new application. 4. Application or patent number(s): B. Patent No.(s) A. Patent Application No.(s) This application

	Additional numbers attached	Yes X No
5. Name and address to whom correspondence concerning document should be mailed:		6. Total number of applications and patents involved:
Name:	Christopher M. Tobin RADER, FISHMAN & GRAUER PLLC	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00
	dress: Atty. Dkt.: SON-4076 ress: 1233 20th Street, N.W. Suite 501	Authorized to be charged by credit card  X Authorized to be charged to deposit account  Enclosed  None required (government interest not affecting title)
City:	Washington	8. Payment Information
State:	DC zip: 20036 hber: (202) 955-3750	a. Credit Card Last 4 Numbers Expiration Date
Fax Numbe	er: (202) 955-3751	b. Deposit Account Number 18-0013 Authorized User Name Christopher M. Tobin
9. Signature		October 2, 2008  Date
	Christopher M. Tobin - 40,290 Ronald P. Kananen – 24,104 Name of Person Signing	Total number of pages including cover sheet, attachments, and documents:

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**PATENT** REEL: 021706 FRAME: 0292

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SON-4076	
Docket Number:	

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor. only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements SEMICONDUCTOR INTEGRATED CIRCUIT for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my and address; AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be g therefor in the United States and in any and all foreign countries; NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration of the sum of One Dollar (\$1.00), and other good an the receipt and sufficience of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these prese hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, tit interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all I Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all p rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Conv Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of Ar adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or secur patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to iss said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto; And I further agree to execute all necessary or desirable and lawful future documents, including assignments in fa-ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said inve applications and Letters Patent of the United States and countries foreign thereto; And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reis reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter requir prepare at its own expense; And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and docu relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be know accessible to me and will testify as to the same in any interference or litigation related thereto; ' And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into would conflict with this assignment and sale. And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing d this application in the spaces that follow: Serial Number: \_\_\_\_\_\_ Filing Date:\_\_\_\_\_\_ This assignment executed on the dates indicated below. Hiromi OGATA Name of first or sole inventor Execution date of U.S. Patent Applic Kanagawa, Japan Residence of first or sole inventor Hiromi Ogata
Signature of first or sole inventor September 19 200A

**RECORDED: 10/02/2008** 

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